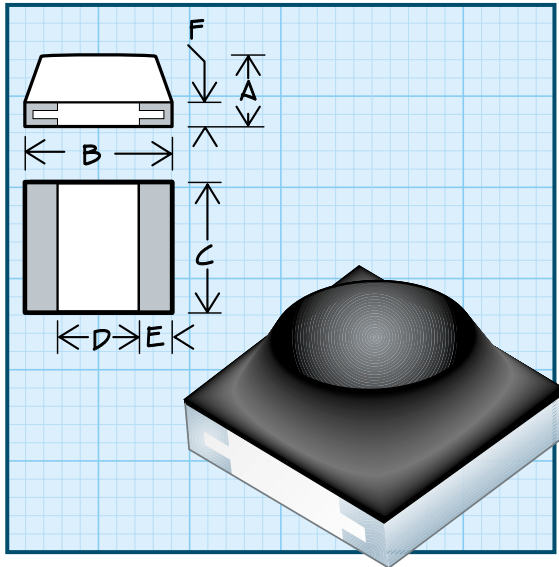


Micro i® Low Profile Chip Inductors



Physical Parameters

	Inches	Millimeters
A	0.050 Max.	1.27 Max.
B	0.100±0.010	2.54±.254
C	0.100±0.010	2.54±.254
D	0.050 Min.	1.27 Min.
E	0.015 Min. (Typ)	0.38 Min. (Typ)
F	0.020 Max. (Typ)	0.51 Max. (Typ)

Current Rating at 90°C Ambient 35°C Rise

Operating Temperature Range -55°C to +125°C

Maximum Power Dissipation at 90°C 0.105 W

Core Material Powdered iron core for improved temperature stability.

Mechanical Configuration Units are epoxy encapsulated. Contact area for reflow soldering are gold plated per MIL-G-45204 Type 1 Grade A. Internal connections are thermal compression bonded.

Termination Finish Options

Standard: Gold over Nickel.

For Tin/Lead over Nickel: Add suffix "S" to part number and allow an additional .010 inch for maximum height. For RoHS, order 3090R - XXXKS.

Packaging Tape & reel (8mm): 7" reel, 2000 pieces max.; 13" reel, 8000 pieces max.

MIL-PRF-83446 (Reference) for testing methods only.

Made in the U.S.A.

DASH NUMBER*
INDUCTANCE (µH)
TOLERANCE
Q MINIMUM
TEST FREQUENCY (MHz)
SRF MINIMUM (MHz)
DC RESISTANCE MAXIMUM (OHMS)
CURRENT RATING MAX. (mA)

SERIES 3090 IRON CORE							
-100M	0.010	± 20%	42	50.0	1000	0.095	890
-150M	0.015	± 20%	42	50.0	1000	0.115	810
-220M	0.022	± 20%	40	50.0	1000	0.140	765
-330K	0.033	± 10%	40	50.0	900	0.185	640
-390K	0.039	± 10%	40	50.0	900	0.100	870
-470K	0.047	± 10%	38	50.0	900	0.110	830
-560K	0.056	± 10%	35	50.0	800	0.135	750
-680K	0.068	± 10%	30	50.0	700	0.16	690
-820K	0.082	± 10%	25	50.0	650	0.19	630
-101K	0.10	± 10%	32	25.0	510	0.08	970
-121K	0.12	± 10%	32	25.0	410	0.10	870
-151K	0.15	± 10%	32	25.0	370	0.12	795
-181K	0.18	± 10%	32	25.0	330	0.14	765
-221K	0.22	± 10%	34	25.0	300	0.16	690
-271K	0.27	± 10%	34	25.0	250	0.20	615
-331K	0.33	± 10%	34	25.0	220	0.25	550
-391K	0.39	± 10%	34	25.0	200	0.30	500
-471K	0.47	± 10%	34	25.0	180	0.36	460
-561K	0.56	± 10%	34	25.0	160	0.45	410
-681K	0.68	± 10%	30	25.0	140	0.50	390
-821K	0.82	± 10%	28	25.0	120	0.60	355
-102K	1.00	± 10%	24	25.0	100	0.70	330
-122K	1.20	± 10%	24	7.9	95	1.10	265
-152K	1.50	± 10%	24	7.9	90	1.20	250
-182K	1.80	± 10%	24	7.9	85	1.25	245
-222K	2.20	± 10%	25	7.9	80	1.30	240
-272K	2.70	± 10%	25	7.9	70	1.50	225
-332K	3.30	± 10%	25	7.9	65	1.90	200
-392K	3.90	± 10%	25	7.9	60	2.30	180
-472K	4.70	± 10%	24	7.9	55	3.00	160
-562K	5.60	± 10%	22	7.9	53	3.50	145
-682K	6.80	± 10%	22	7.9	50	4.00	135
-822K	8.20	± 10%	22	7.9	45	4.50	130
-103K	10.0	± 10%	20	7.9	40	5.00	120

Optional Tolerances: J = 5% H = 3% G = 2% F = 1%

*Complete part # must include series # PLUS the dash #

For further surface finish information, refer to TECHNICAL section of this catalog.

Notes 1) Designed specifically for reflow soldering and other high temperature processes with metalized edges to exhibit solder fillet. 2) Self Resonant Frequency (SRF) values 250 MHz and above are calculated and for reference only.